

L Number	Hits	Search Text	DB	Time stamp
3	20	"529879"	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/08/02 15:53
4	117	hewlett and (slot\$3 adj substrate\$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/08/02 15:54
5	20	("5317346" "5387314" "5519423" "5751317" "5980017" "6003986" "6019457" "6039437" "6053599" "6062681" "6109744" "6113223" "6132033" "6161923" "6199980" "6224197" "6270198" "6280642" "6299673" "6331055" "2001/0003460").PN.	USPAT	2004/08/02 15:55
6	1		USPAT	2004/08/02 15:57
7	1		USPAT	2004/08/02 15:58
8	1		USPAT	2004/08/02 15:58
9	1		USPAT	2004/08/02 15:58
10	1		USPAT	2004/08/02 16:00
11	1		USPAT	2004/08/02 16:00
12	1		USPAT	2004/08/02 16:01
13	1		USPAT	2004/08/02 16:01
14	1		USPAT	2004/08/02 16:02
15	1		USPAT	2004/08/02 16:02
-	2	6672712.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/08/02 10:53
-	10687	(substrate with thick\$) and ((trench\$ slot\$) with surface\$)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/06/10 16:03
-	218	((substrate with thick\$) and ((trench\$ slot\$) with surface\$)) and 347/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/06/10 16:18
-	322	(substrate with thick\$) and (axis same ((trench\$ slot\$) with surface\$))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/06/10 16:18
-	16	((substrate with thick\$) and (axis same ((trench\$ slot\$) with surface\$))) and 347/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/06/10 16:25
-	0	20040085408.URPN.	USPAT	2004/06/10 16:25
-	11	("1597487" "2672072" "3349174" "3441948" "3465352" "3534166" "3549826" "3720784" "3732363" "3811009" "3836225").PN.	USPAT	2004/06/10 16:27
-	20	("5317346" "5387314" "5519423" "5751317" "5980017" "6003986" "6019457" "6039437" "6053599" "6062681" "6109744" "6113223" "6132033" "6161923" "6199980" "6224197" "6270198" "6280642" "6299673" "6331055" "2001/0003460").PN.	USPAT	2004/06/10 16:28
-	3	("5006202" "6107209" "6273557").PN.	USPAT	2004/06/10 16:30
-	24	("5066357" "5317346" "5361087" "5378137" "5441593" "5449630" "5588597" "5658471" "5719604" "5786988" "5820919" "5847725" "5910679" "5953029" "5988786" "6020270" "6106096" "6107158" "6133926" "6142611" "6184570" "6315397" "6331055" "6348396" "2001/0023979").PN.	USPAT	2004/06/10 16:31
-	21	("5317346" "5387314" "5519423" "5751317" "5980017" "6003986" "6019457" "6039437" "6053599" "6062681" "6109744" "6113223" "6132033" "6161923" "6199980" "6224197" "6270198" "6273557" "6280642" "6299673" "6331055" "2001/0003460").PN.	USPAT	2004/06/10 16:31

-	1	(substrate near (trench with (hole\$1 slot\$1))) and inkjet	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/07/14 18:05
-	5	(substrate near (trench with (hole\$1 slot\$1)))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/07/14 18:37
-	278	silverbrook-\$.in. and 347/54.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/07/14 18:40
-	3	(silverbrook-\$.in. and 347/54.ccls.) and (substrate near chamber)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/07/14 18:40
-	10	(silverbrook-\$.in. and 347/54.ccls.) and (substrate near channel\$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/07/14 18:39
-	635	silverbrook-\$.in. and 347/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/07/14 18:40
-	3	(silverbrook-\$.in. and 347/\$.ccls.) and (substrate near chamber)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/07/14 18:40
-	308	(silverbrook-\$.in. and 347/\$.ccls.) and (nozzle adj arrangement\$1)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/07/14 18:41
-	233	((silverbrook-\$.in. and 347/\$.ccls.) and (nozzle adj arrangement\$1)) and (hole\$1 slot\$1 trench)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/07/14 18:41
-	229	((silverbrook-\$.in. and 347/\$.ccls.) and (nozzle adj arrangement\$1)) and (hole\$1 slot\$1 trench)) and substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/07/15 11:09
-	8869	(semiconductor with (slot\$3 etch\$3 hole\$1)) same trench	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/07/15 11:10
-	7429	(semiconductor with (slot\$3 etch\$3 hole\$1) with trench)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/07/15 14:54
-	7	((semiconductor with (slot\$3 etch\$3 hole\$1) with trench)) and 347/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/07/15 13:30
-	10	("3621442" "3941629" "4028945" "4079508" "4203128" "4347976" "4432007" "4516148" "4581624" "4637071").PN.	USPAT	2004/07/15 11:16
-	15	("4680859" "4862197" "4866460" "5016023" "5098503" "5133495" "5160945" "5203075" "5369880" "5442384" "5453581" "5534898" "5589865" "6099109" "6325548").PN.	USPAT	2004/07/15 11:18
-	14	("4680859" "4862197" "4866460" "5016023" "5098503" "5133495" "5160945" "5203075" "5369880" "5442384" "5453581" "5534898" "5589865" "6099109").PN.	USPAT	2004/07/15 11:21
-	8	("5159353" "5665249" "5710070" "5774148" "5783474" "5841452" "5850241" "5900894").PN.	USPAT	2004/07/15 11:22

-	91	substrate\$1 with slot\$1 with trench	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/07/15 13:31
-	889	(semiconductor with (slot\$3 passage\$1 groove\$1) with trench)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/07/15 14:55
-	0	((semiconductor with (slot\$3 passage\$1 groove\$1) with trench)) and 347/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/07/15 14:54
-	915	(semiconductor with (slot\$3 slit\$1 passage\$1 groove\$1) with trench)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/07/15 14:55
-	64	((semiconductor with (slot\$3 slit\$1 passage\$1 groove\$1) with trench)) and microns	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/07/15 14:55
-	2	5953029.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/08/02 10:54
-	2	5441593.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/08/02 12:00